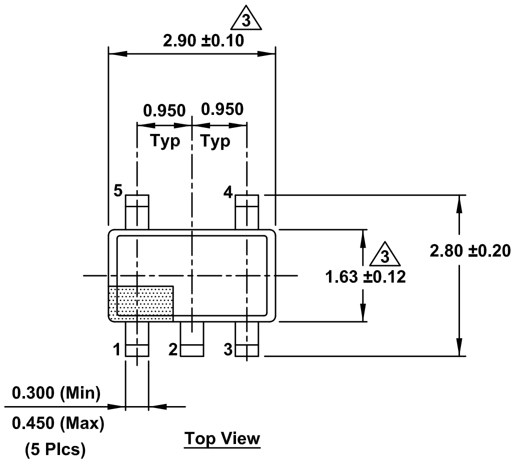
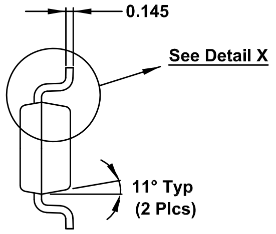
Package Outline Drawing

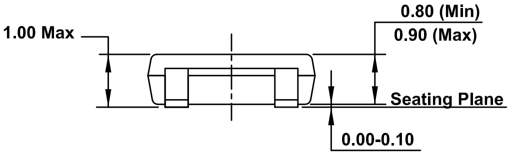
P5.064D
5 Lead Thin Small Outline Transistor (TSOT) Plastic Package
Rev 0, 11/2021



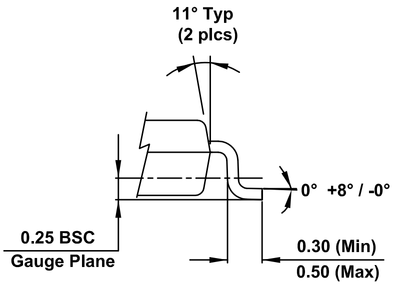
Top View



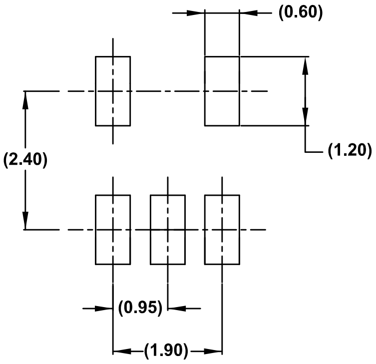
End View



Side View



Detail X



Typical Recommended Land Pattern

NOTE:

1. Dimensioning and tolerancing conform to ASME Y14.5m-1994.
2. Die is facing up for mold. Die is facing down for trim/form, that is reverse trim/form.
3. Dimensions are exclusive of mold flash and gate burr.
4. The footlength measuring is based on the gauge plane method.
5. All specifications comply to JEDEC Spec MO193 Issue C.
6. Dimensions in mm.